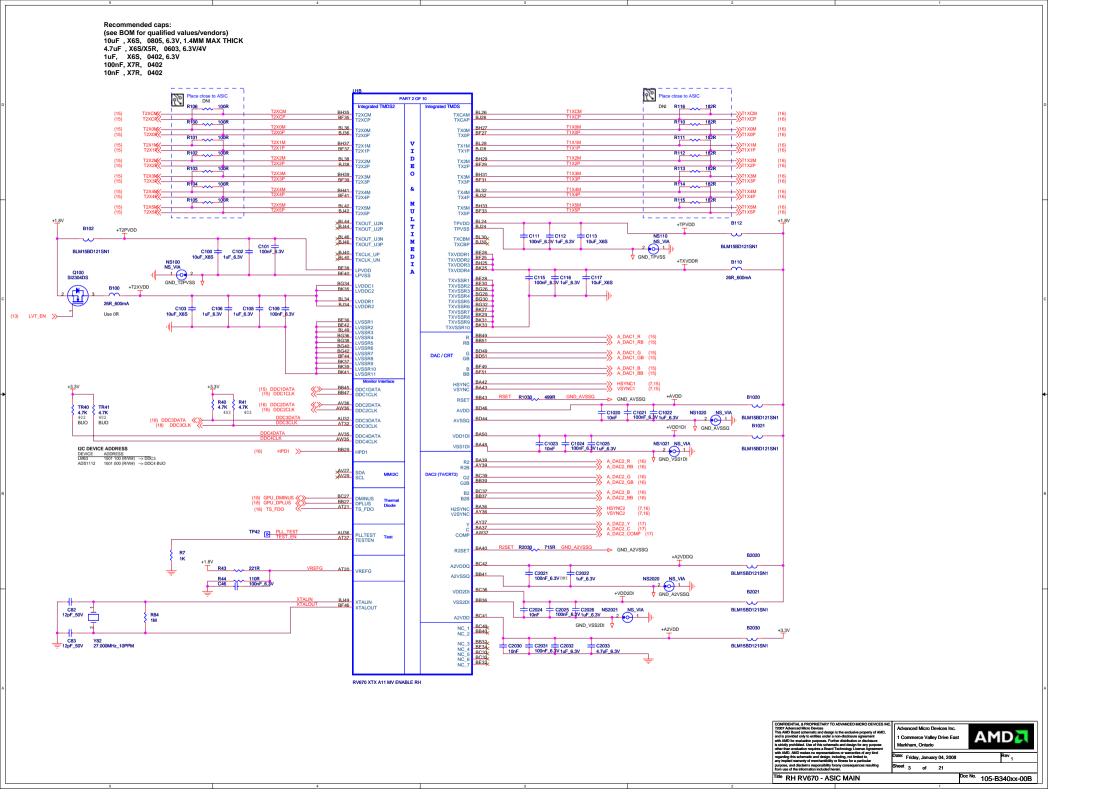
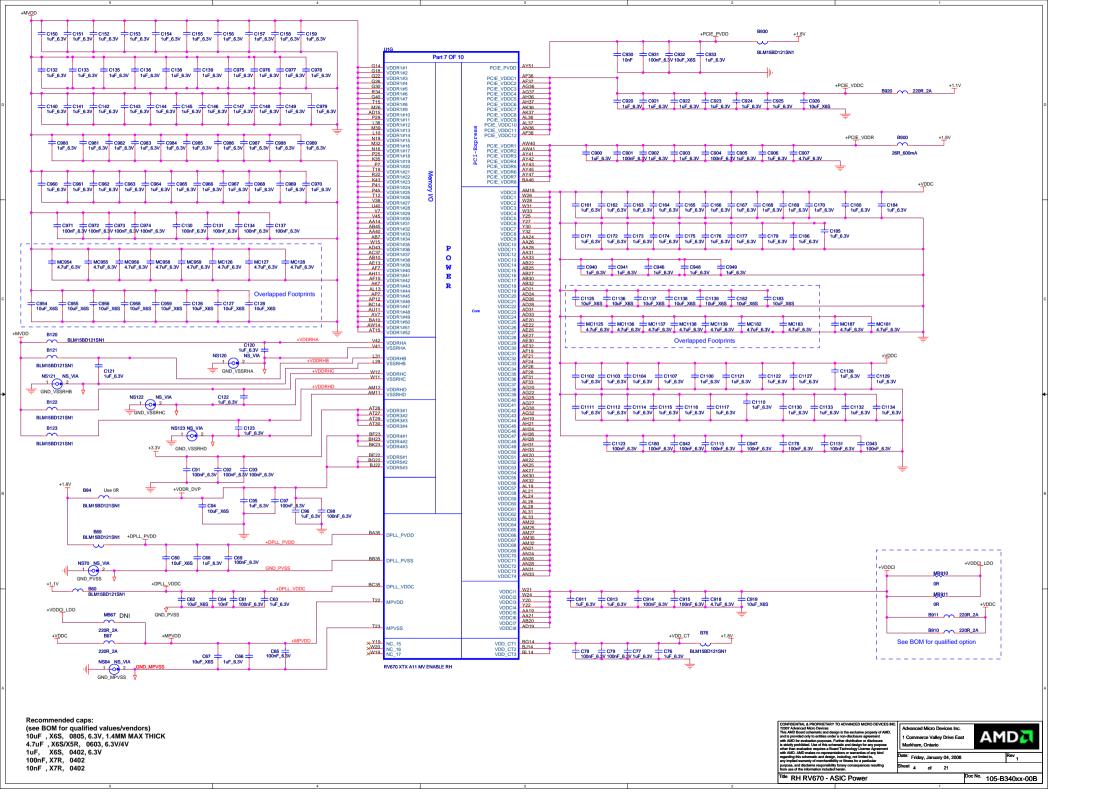
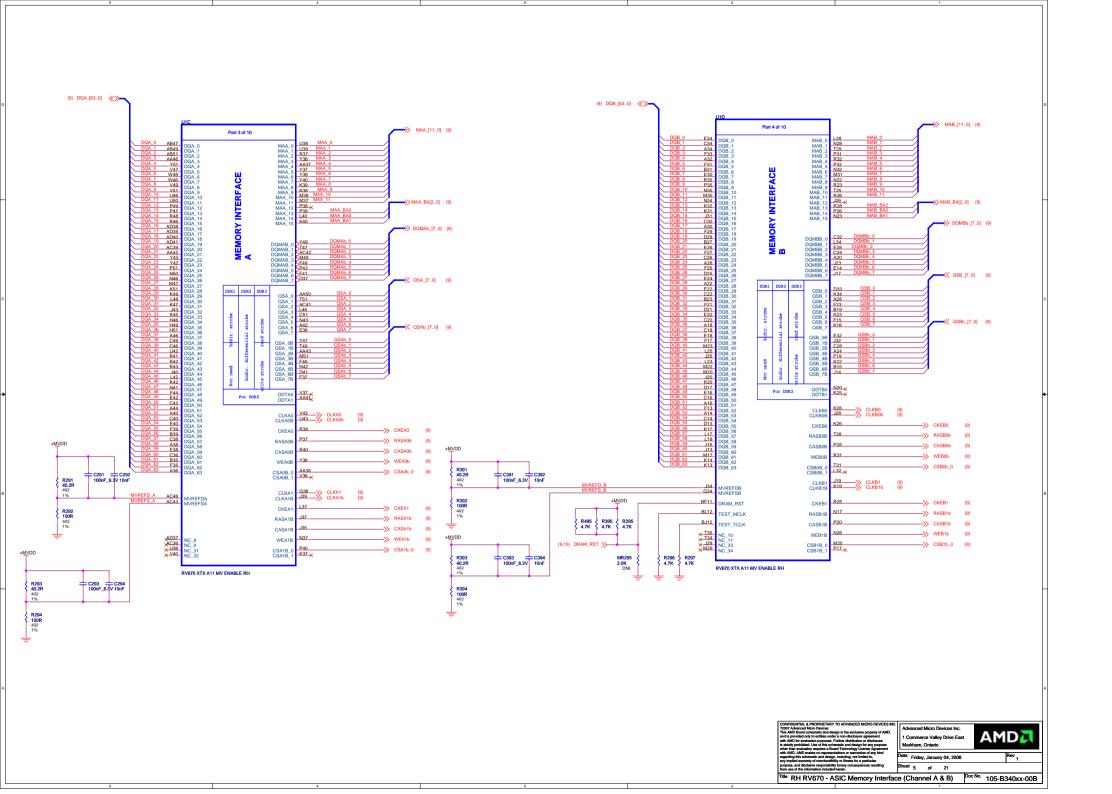
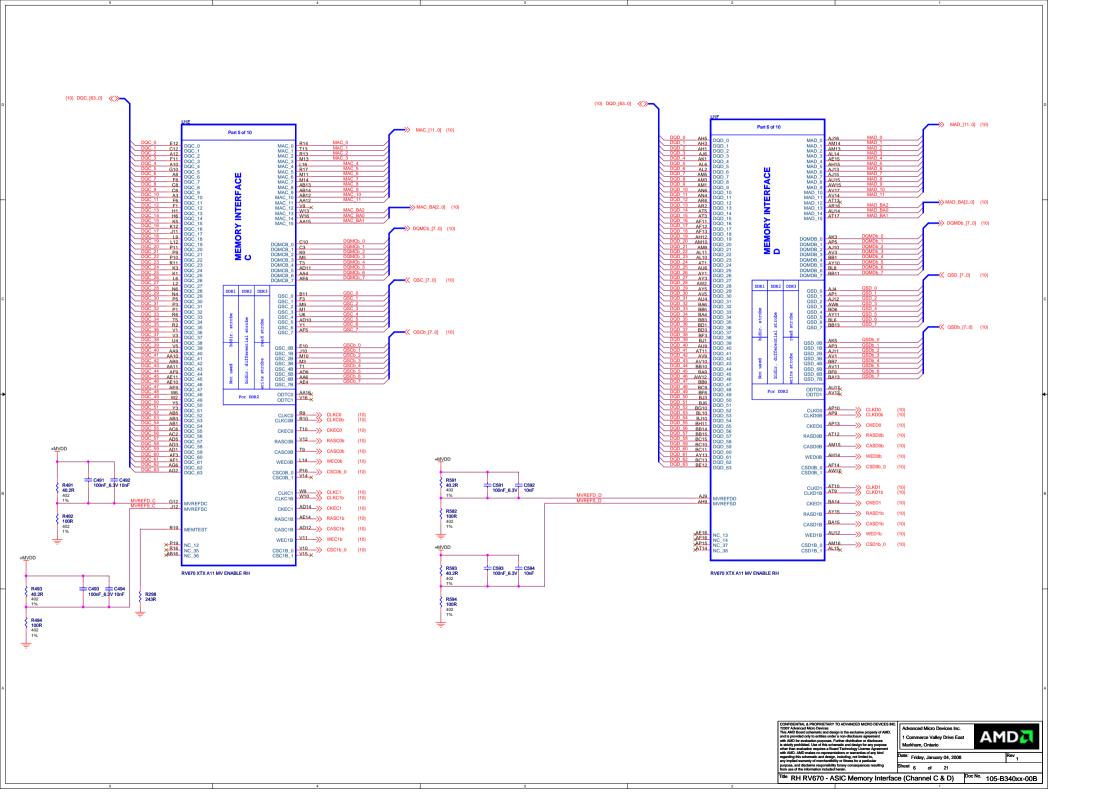


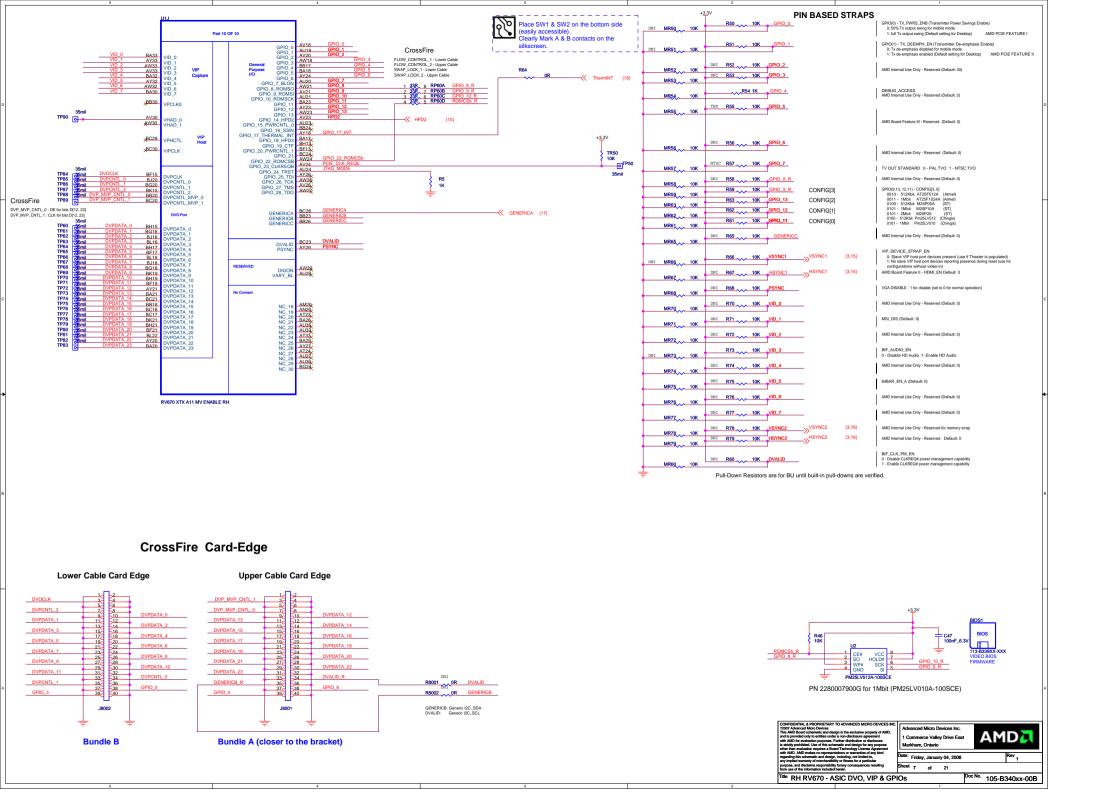
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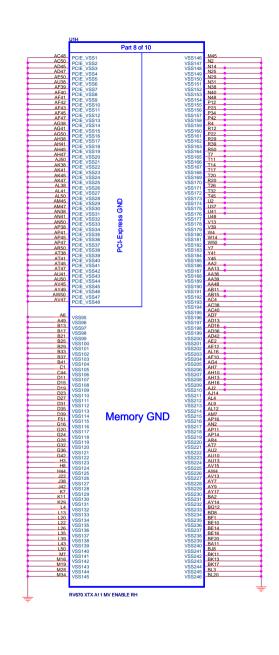


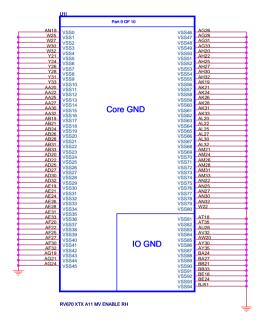




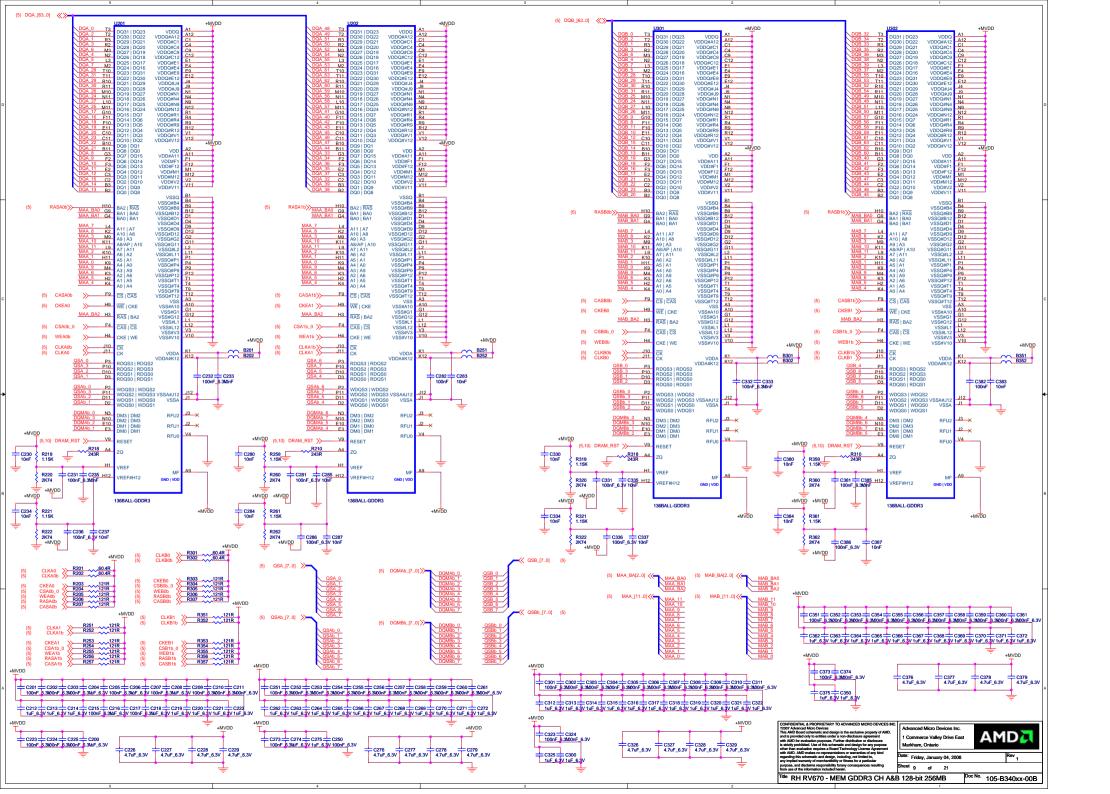


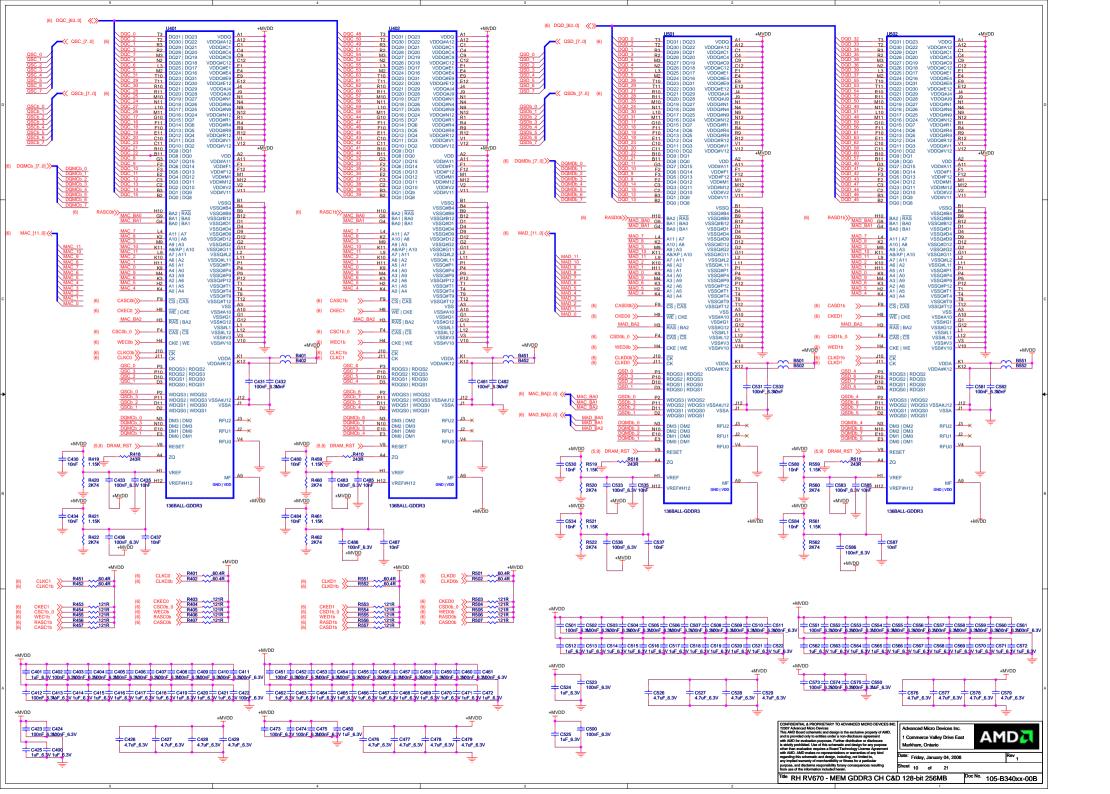


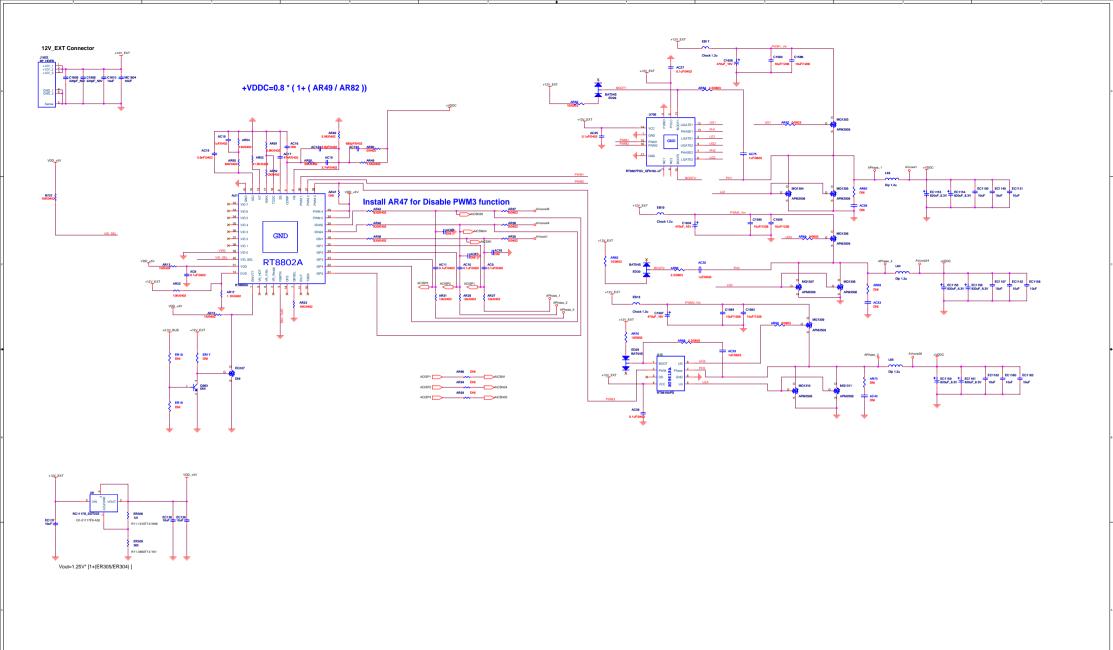




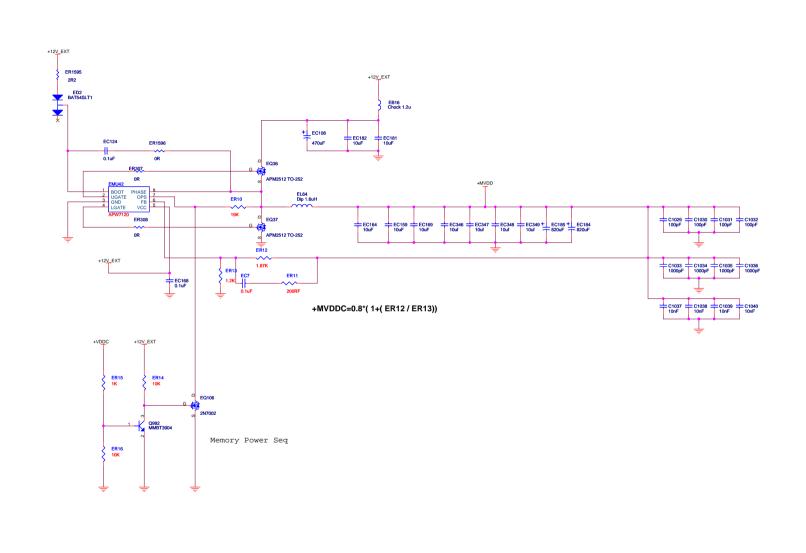
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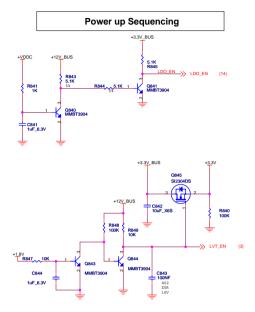








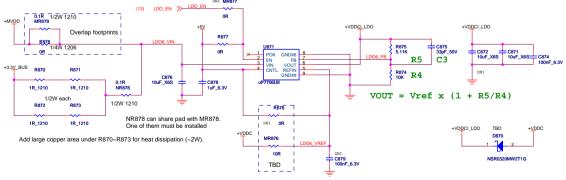
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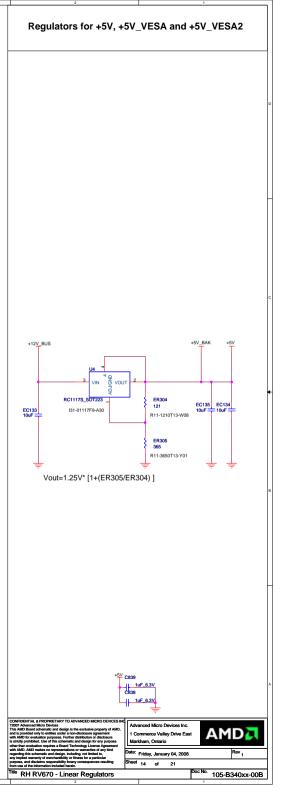


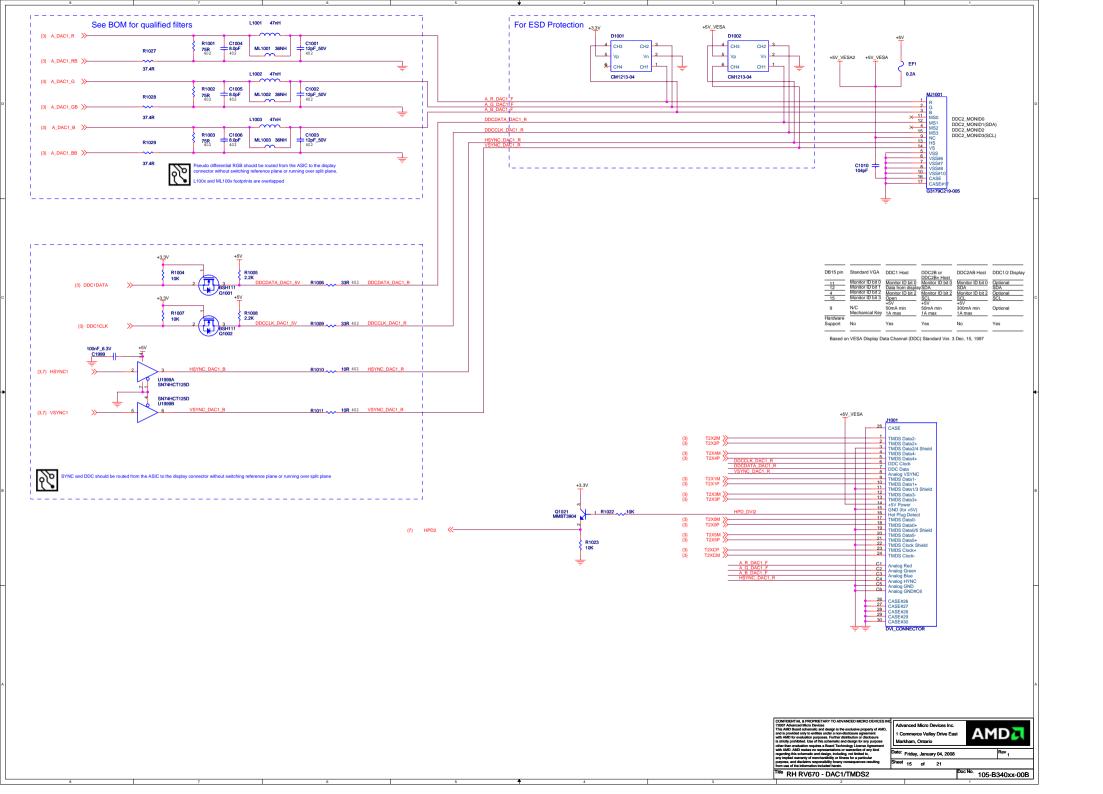


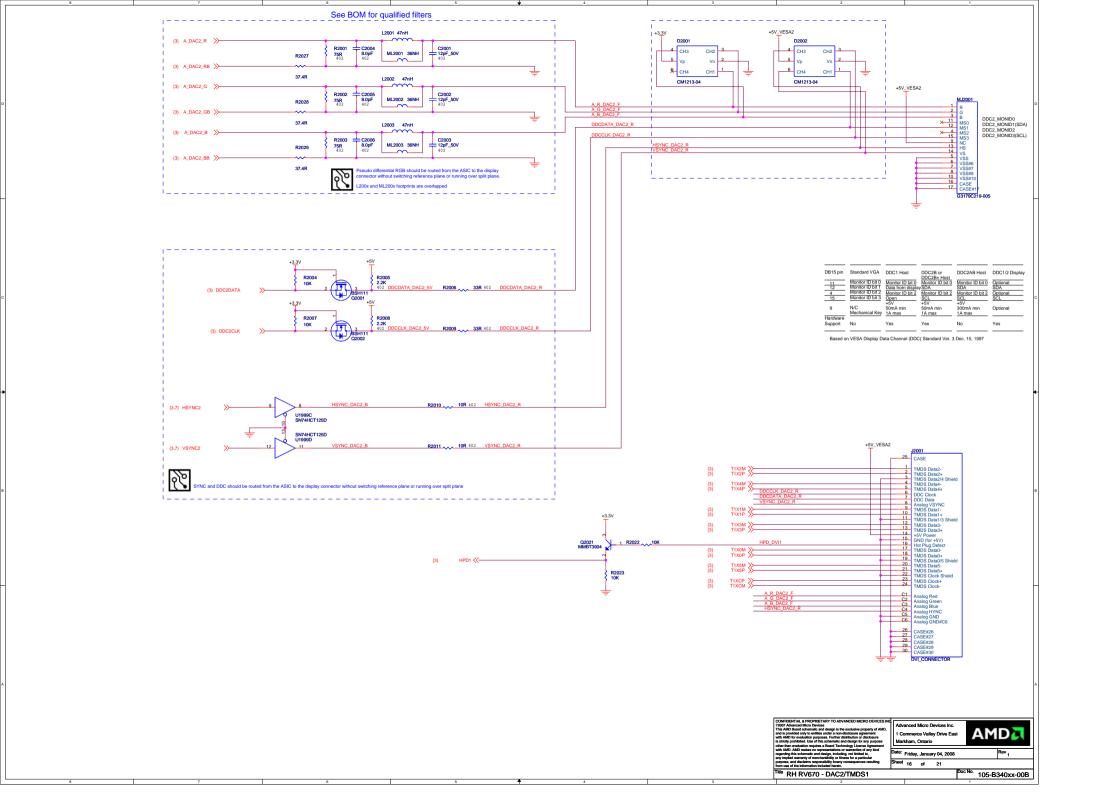
LDO #2: Vin = 2.5V to 3.6V MAX Vout = +1.8V +/- 3% lout = 0.8A (TBV) RMS MAX PCB: 50 to 70mm sq. copper area for cooling R868 Overlap footprints C865 33pF_50V R5 VOUT = Vref x (1 + R5/R4)LDO #3: Vin = +1.70V to 2.1VMAX Vout = +1.1V +/- 3% lout = Up to 1.3A (TBV) RMS MAX PCB: 50 to 70mm sq. copper area for cooling Overlap footprints R858 R855 C855 33pF_50V R5 R854 R4 VOUT = Vref x (1 + R5/R4)LDO #6: For fixed output voltage: Vin = +1.70V to 2.1V MAX Vout = +1.20V +/- 3% lout = 1.3A (TBV) RMS MAX PCB: 50 to 70mm sq. copper area for cooling LDO #6: For tracking VDDC: Vin = TBD Vout = TBD PCB: 50 to 70mm sq. copper area for cooling

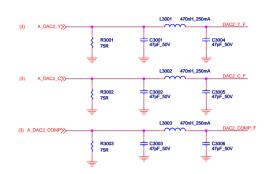
lout = 1.3A (TBV) RMS MAX

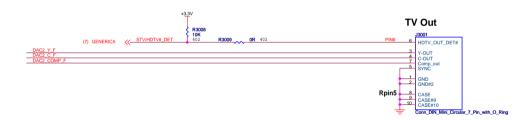






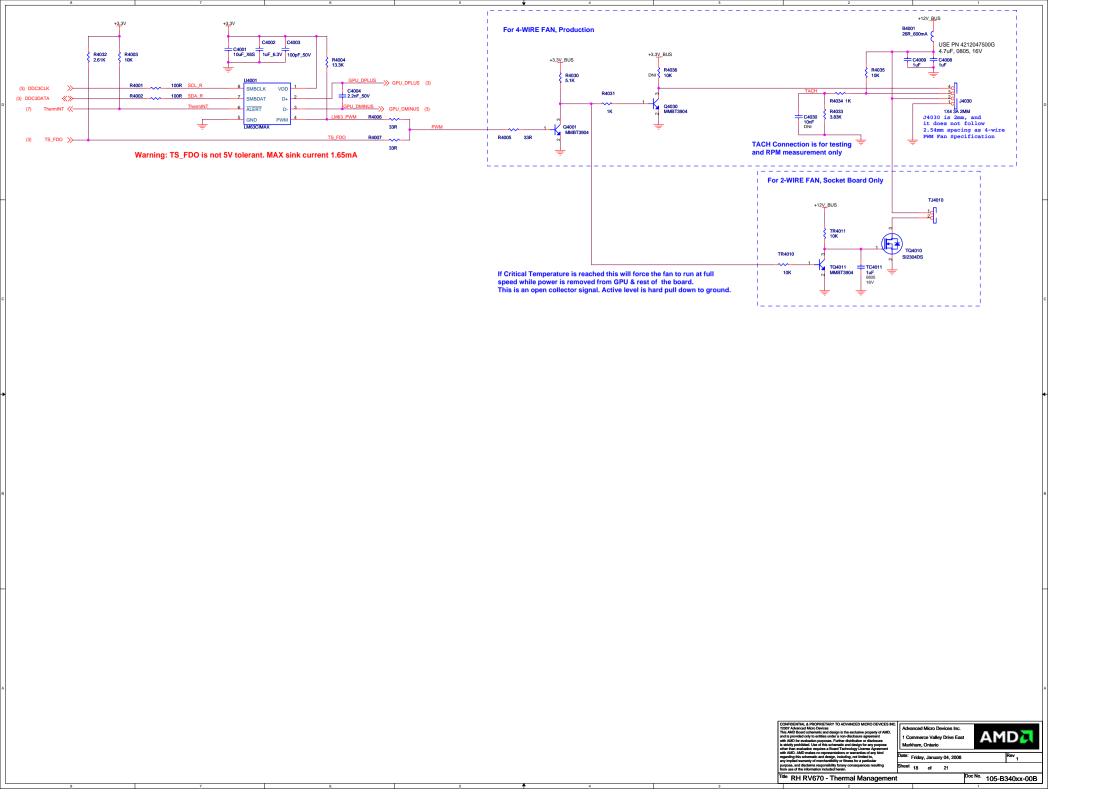


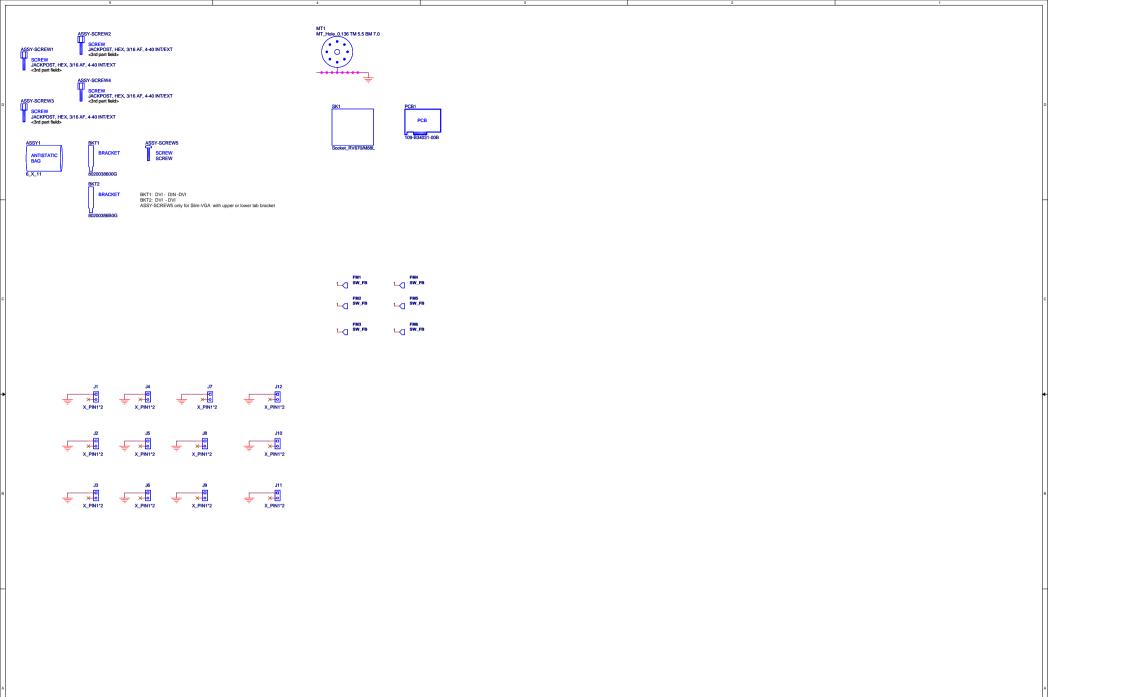




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	Δ	MD	5	Title RH PCIE RV670 512MB GDDR3 DUAL DL-DVI-I VO F	Н	Schematic No. 105-B340xx-00B	Date: Friday, January 04,	2008	
AMD			REVISION HISTORY	For Stuffing options (cor	he PCB, it does not represent any specific SKU. onent values, DNI , ? please consult the product specific BOM. entative to obtain latest BOM closest to the application desired.				
L	Sch Rev	PCB Rev	Date	REVISION DESCRIPTION					
	0	A00	07/05/11	Initial design for RV670 GDDR3 (Revival) based on B339					
	1	00B	07/08/1	(pg 1) Adding R1 and connecting switch #7 of TSW1. Some mother boards require B7 to be grounded. Table-1 updated accordingly (pg 7) Adding R64 and MR64 to select HOT_PLUG_DET or ThermINT as the interrupt source. (pg 13) Adding R1617, MR1617, R1616, Q1613, R1615, R1618, and R1619 as option to support hot plug detection of external cable. (pg 13) Adding R1282, MR1282, R1283, MR1284, MR1284, R1281, R1285, Q1280, and C1280 as option for thermal protection for VDDC SMPS MOSFETs (pg 13) Adding MC1603 (overlapped with C1603) (pg 14) Adding D870 as option for power up sequencing (pg 18) Adding heatsink symbol/footprint (Layout) Increasing spacing between DDC4DATA & DDC4CLK going to U1270 to reduce the crosstalk					
В									
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			5	4	3	2	1		

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